



**YEA SHIN TECHNOLOGY CO., LTD**

**YS3910ZBB**

**N-Channel Enhancement MOSFET**  
**VDS= 30V, ID= 35A**



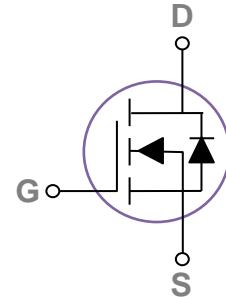
**Features**

- 30V,35A,  $R_{DS(ON)} = 12m\Omega$ (Typ)@ $V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

**Applications**

- MB / VGA / Vcore
- POL Buck Applications
- SMPS 2<sup>nd</sup> SR

**PPAK3x3 Pin Configuration**



**Absolute Maximum Rating**  $T_c=25^\circ C$  unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	35	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	22	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	140	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	13	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	16	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	27	W
	Power Dissipation – Derate above $25^\circ C$	0.21	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	4.6	$^\circ C/W$

# DEVICE CHARACTERISTICS

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Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=10\text{A}$	---	9.4	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=5\text{A}$	---	13	18	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=10\text{A}$	---	6.4	---	S

### Dynamic and Switching Characteristics

$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=5\text{A}$	---	7.4	12	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3,4</sup>		---	2.3	5	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3,4</sup>		---	3	6	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3,4</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=6\Omega$ , $I_{\text{D}}=1\text{A}$	---	3.8	7	ns
$T_r$	Rise Time <sup>3,4</sup>		---	10	19	
$T_{\text{d(off)}}$	Turn-On Delay Time <sup>3,4</sup>		---	22	42	
$T_f$	Fall Time <sup>3,4</sup>		---	6.6	13	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	620	900	pF
$C_{\text{oss}}$	Output Capacitance		---	85	125	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	60	90	
$R_g$	Gate Resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.8	5.6	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	35	A
$I_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	70	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_{\text{s}}=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=16\text{A}$ ,  $R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

# DEVICE CHARACTERISTICS

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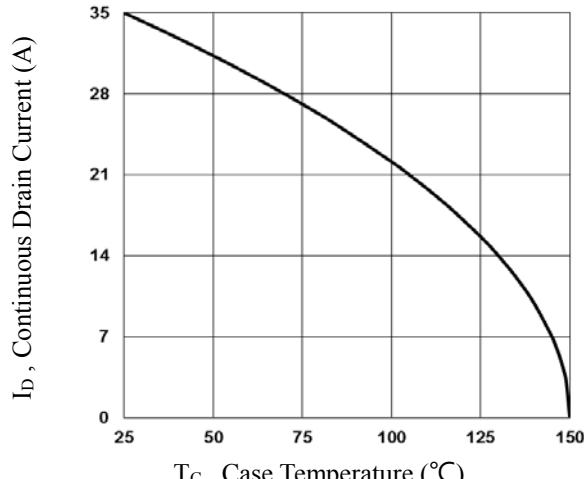


Fig.1      Continuous Drain Current vs.  $T_c$

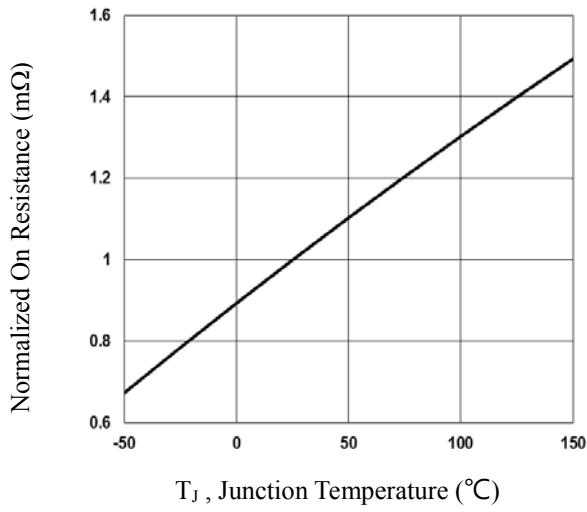


Fig.2      Normalized RDS(on) vs.  $T_j$

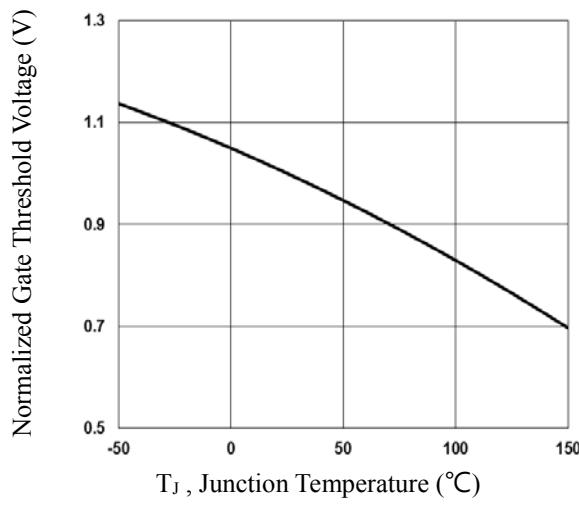


Fig.3      Normalized  $V_{th}$  vs.  $T_j$

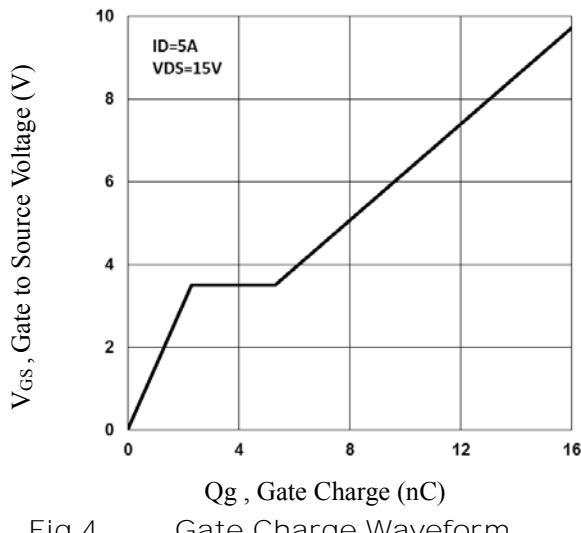


Fig.4      Gate Charge Waveform

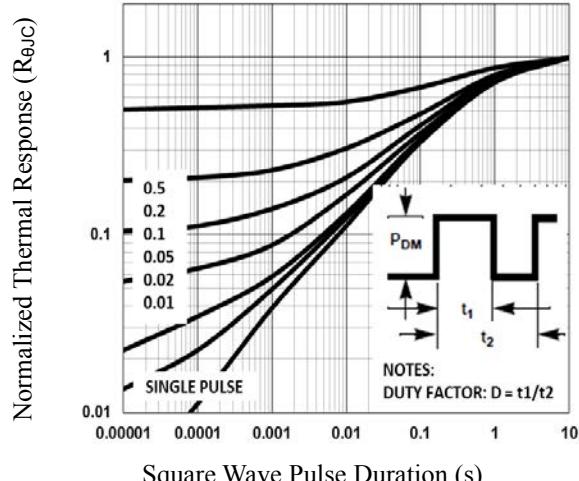


Fig.5      Normalized Transient Impedance

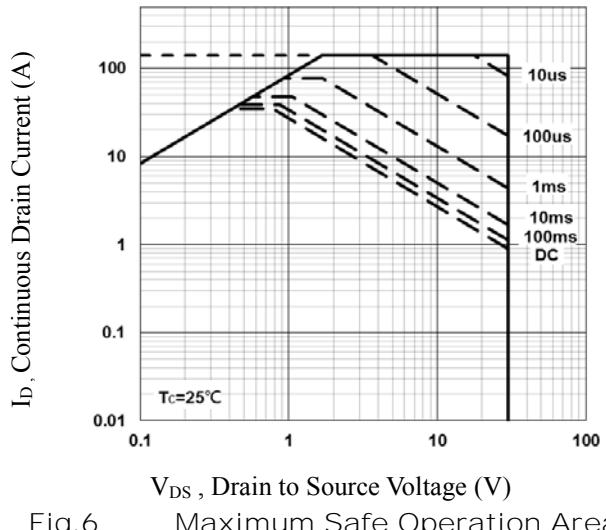


Fig.6      Maximum Safe Operation Area

# DEVICE CHARACTERISTICS

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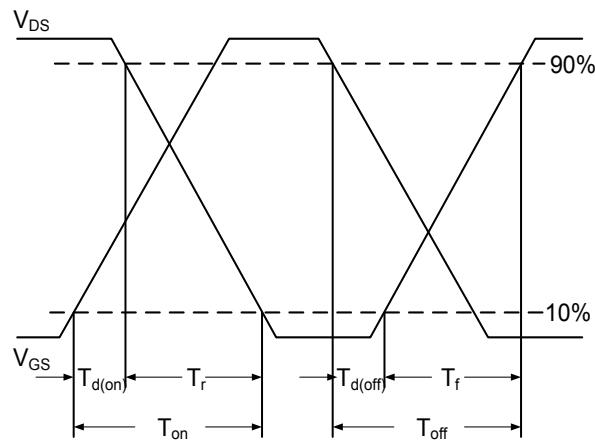


Fig.7 Switching Time Waveform

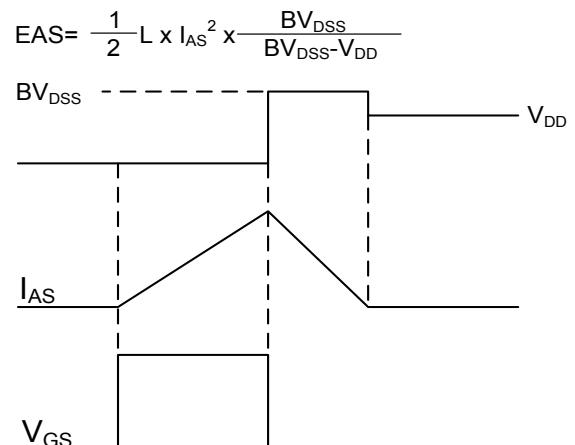
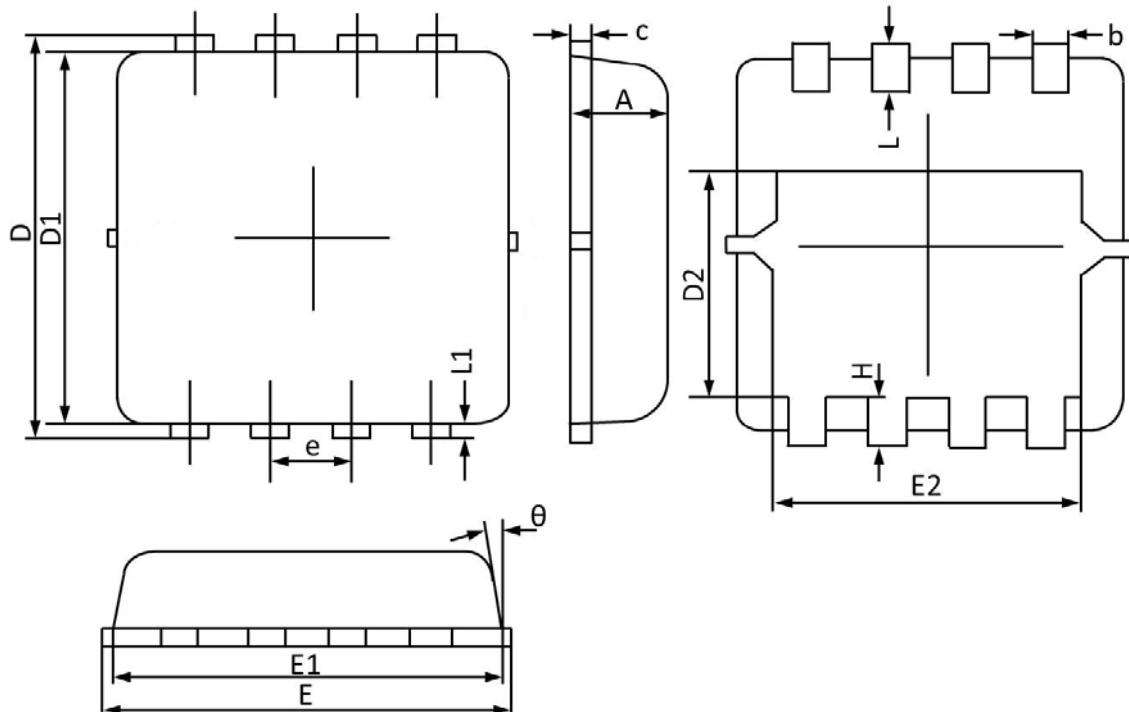


Fig.8 EAS Waveform

# PACKAGE OUTLINE & DIMENSIONS

YS3910ZBB

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.900	0.028	0.035
b	0.240	0.350	0.009	0.014
c	0.100	0.250	0.004	0.010
D	3.050	3.450	0.120	0.136
D1	2.900	3.200	0.114	0.126
D2	1.350	1.850	0.053	0.073
E	3.000	3.400	0.118	0.134
E1	2.900	3.250	0.114	0.128
E2	2.350	2.600	0.093	0.102
e	0.65BSC		0.026BSC	
H	0.300	0.500	0.012	0.020
L	0.300	0.500	0.012	0.020
L	0.070	0.200	0.003	0.008
θ	0 °	12 °	0 °	12 °